ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SO-8 SOLDER PROCESS					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
BOND INT	300	150,000	200°C + N2	0	0.00
HAST	2,102	207,450	130°C, 85%RH	0	0.00
Power Cycle	306	4,204,320	DELTA T_j = 100	0	0.00
Pressure Pot	7,514	754,764	121°, 15 PSIG	0	0.00
Solder DUNK	1,000	3,000	260°C, 10SEC	0	0.00
Solderability	255	2,040	883 M2003	0	0.00
Temp Cycle	15,170	6,357,500	−65°C−150°C	0	0.00
Thermal Shock	200	20,000	−60°C−150°C	0	0.00